Silicon N Channel MOS FET High Speed Power Switching

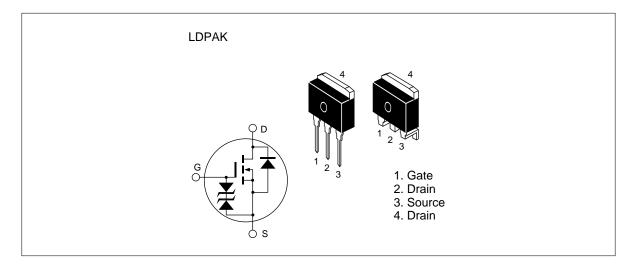
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ADE-208-760(Z) Target Specification, 1st. Edition Dec. 1, 1998

Features

- Low on-resistance
 - R_{DS} =35m Ω typ.
- High speed switching
- 4V gate drive device can be driven from 5V source

Outline



Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit V	
Drain to source voltage	V _{DSS}	150		
Gate to source voltage	V _{GSS}	±20	V	
Drain current	I _D	30	A	
Drain peak current	Note1	120	A	
Body-drain diode reverse drain current	I _{DR}	30	A	
Avalanche current	I AP Note3	30	A	
Avalanche energy	E _{AR} ^{Note3}	67	mJ	
Channel dissipation	Pch Note2	100	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Note: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at Tc = $25^{\circ}C$

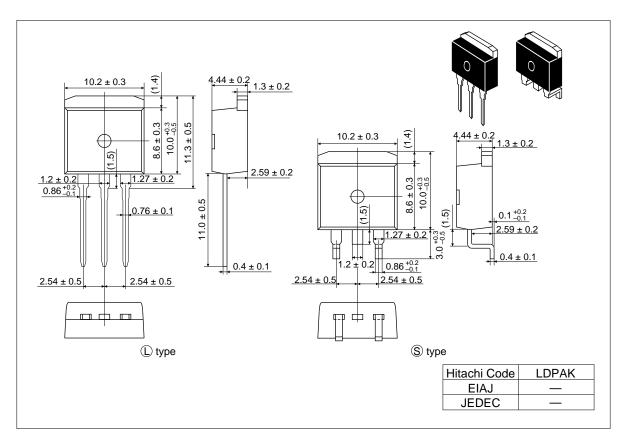
3. Value at Tch = 25° C, Rg $\geq 50\Omega$

Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	150	_	_	V	$I_{\rm D} = 10 {\rm mA}, V_{\rm GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±20			V	$I_{g} = \pm 100 \mu A, V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μA	$V_{GS} = \pm 16V, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 150 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	1.0		2.5	V	$I_{\rm D} = 1$ mA, $V_{\rm DS} = 10$ V
Static drain to source on state	R _{DS(on)}	_	35	45	mΩ	$I_{\rm D} = 15$ A, $V_{\rm GS} = 10$ V ^{Note4}
resistance	R _{DS(on)}	_	42	75	mΩ	$I_{\rm D} = 15$ A, $V_{\rm GS} = 4$ V ^{Note4}
Forward transfer admittance	y _{fs}	18	30		S	$I_{\rm D} = 15$ A, $V_{\rm DS} = 10$ V ^{Note4}
Input capacitance	Ciss		2600	_	pF	V _{DS} = 10V
Output capacitance	Coss		820		pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss		350		pF	f = 1MHz
Turn-on delay time	t _{d(on)}	_	25	_	ns	$I_{\rm D} = 15$ A, $V_{\rm GS} = 10$ V
Rise time	t,		180		ns	$R_L = 2\Omega$
Turn-off delay time	t _{d(off)}		600		ns	
Fall time	t _f	_	280	_	ns	
Body-drain diode forward voltage	V _{DF}	_	0.95		V	$I_{\rm F} = 30A, V_{\rm GS} = 0$
Body–drain diode reverse recovery time	t _{rr}		110		ns	$I_F = 30A$, $V_{GS} = 0$ diF/ dt =50A/µs

Note: 4. Pulse test

Package Dimensions (Unit: mm)



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Hitachi, Ltd.

Semiconductor & IC Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL NorthAmerica Europe Asia (Singapore) Asia (Taiwan) Asia (HongKong) http://www.hitachi.com/ http://www.hitachi.eu.com/hel/ecg http://www.has.hitachi.com.sg/grp3/sicd/index.htm http://www.hitachi.com.tw/E/Product/SICD_Frame.htm http://www.hitachi.com.hk/eng/bo/grp3/index.htm http://www.hitachi.co.jo/Sicd/indx.htm

For further information write to: Hitachi Semiconductor Hitachi Europe GmbH

Hitachi Semiconductor (America) Inc. 2000 Sierra Point Parkway Brisbane, CA 94005-1897 Tel: <1> (800) 285-1601 Fax: <1> (303) 297-0447

Japan

Electronic components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322 Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd. Taipei Branch Office 3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180 Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218 Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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